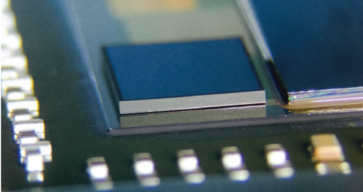
Advanced Packaging Solutions

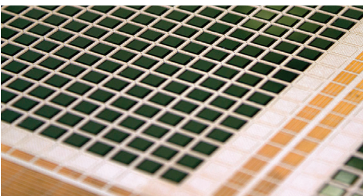
Universal Instruments

Bringing high productivity to advanced packaging assembly

Advanced capabilities for advanced applications:

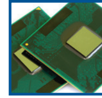


Full range of actives and passives:
Size: 008004 – 100 x 100mm
Thickness: 50µm – 25mm

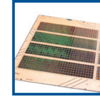


Any substrate format:
Size: 20 x 20mm – 813 x 610mm
Thickness: 50µm – 12.7mm

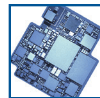
Comprehensive process development



Flip Chip in Package

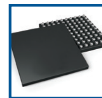


Embedded



System-in-Package

High-Accuracy Place



Wafer-Level Packaging

Multi-Die Fan-Out

FUZION SC

Semiconductor performance at surface mount speeds

One solution for all advanced packaging challenges

- Accuracy: <10µm, speed: 16K cph, area: 813 x 610mm
- Any feeding option (wafer, tray, tape, tube, bulk, direct die)
- Place high-accuracy actives and passives on one platform
- Pick and place on any substrate, including thin/flex
- Advanced Process Lab (APL): Leading-edge process and materials expertise; process optimization, failure analysis

FUZIONSC VIDEO (click here)

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MC-6687B

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